



## Material Content Data Sheet



<b>Sales Product Name</b>		IPA90R340C3		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000468294						
<b>Package</b>		PG-TO220-3-111		<b>Weight*</b>		2242.74 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	13.276	0.59	0.59	5920	5920
leadframe	non noble metal	iron	7439-89-6	1.120	0.05		499	
	inorganic material	phosphorus	7723-14-0	0.336	0.02		150	
	non noble metal	copper	7440-50-8	1118.332	49.87	49.94	498645	499294
wire	non noble metal	aluminium	7429-90-5	2.733	0.12	0.12	1219	1219
encapsulation	organic material	carbon black	1333-86-4	2.186	0.10		975	
	plastics	epoxy resin	-	205.487	9.16		91623	
	inorganic material	silicondioxide	60676-86-0	885.344	39.48	48.74	394760	487358
leadfinish	non noble metal	tin	7440-31-5	7.942	0.35	0.35	3541	3541
plating	non noble metal	nickel	7440-02-0	0.305	0.01		136	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	0	136
solder	non noble metal	antimony	7440-36-0	0.568	0.03		253	
	noble metal	silver	7440-22-4	1.420	0.06		633	
	non noble metal	tin	7440-31-5	3.693	0.16	0.25	1646	2532
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com